

Single N-channel MOSFET

ELM13404CA-S

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■ General description

ELM13404CA-S uses advanced trench technology to provide excellent $R_{ds(on)}$, low gate charge and low gate resistance.

■ Features

- $V_{ds}=30V$
- $I_d=5.8A$ ($V_{gs}=10V$)
- $R_{ds(on)} < 28m\Omega$ ($V_{gs}=10V$)
- $R_{ds(on)} < 43m\Omega$ ($V_{gs}=4.5V$)

■ Maximum absolute ratings

Parameter	Symbol	Limit	Unit	Note
Drain-source voltage	V_{ds}	30	V	
Gate-source voltage	V_{gs}	± 20	V	
Continuous drain current	I_d	5.8	A	1
Ta=70°C		4.9		
Pulsed drain current	I_{dm}	20	A	2
Power dissipation	P_d	1.4	W	
Ta=70°C		1.0		
Junction and storage temperature range	T_j, T_{stg}	-55 to 150	°C	

■ Thermal characteristics

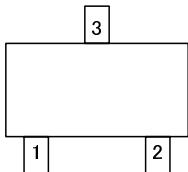
Parameter		Symbol	Typ.	Max.	Unit	Note
Maximum junction-to-ambient	t≤10s	$R_{\theta ja}$	65	90	°C/W	1
Maximum junction-to-ambient	Steady-state		85	125	°C/W	
Maximum junction-to-lead	Steady-state	$R_{\theta jl}$	43	60	°C/W	3

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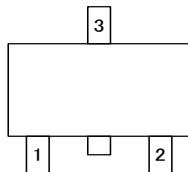
■ Pin configuration

■ Circuit

SOT-23 (TOP VIEW)

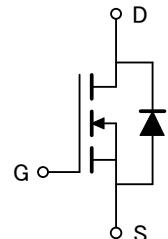


(Without extra bar)



(With extra bar)

Pin No.	Pin name
1	GATE
2	SOURCE
3	DRAIN



■ Electrical characteristics

Ta=25°C

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
STATIC PARAMETERS						
Drain-source breakdown voltage	BVdss	Id=250 μA, Vgs=0V	30			V
Zero gate voltage drain current	Idss	Vds=30V			1	μ A
		Vgs=0V	Tj=55°C		5	
Gate-body leakage current	Igss	Vds=0V, Vgs=±20V			100	nA
Gate threshold voltage	Vgs(th)	Vds=Vgs, Id=250 μ A	1.0	1.9	3.0	V
On state drain current	Id(on)	Vgs=4.5V, Vds=5V	20			A
Static drain-source on-resistance	Rds(on)	Vgs=10V		22.5	28.0	m Ω
		Id=5.8A	Tj=125°C	31.3	38.0	
		Vgs=4.5V, Id=5A		34.5	43.0	
Forward transconductance	Gfs	Vds=5V, Id=5.8A	10.0	14.5		S
Diode forward voltage	Vsd	Is=1A		0.76	1.00	V
Max. body-diode continuous current	Is				2.5	A
Pulsed body-diode current ²	Is				20.0	A
DYNAMIC PARAMETERS						
Input capacitance	Ciss	Vgs=0V, Vds=15V, f=1MHz		680	820	pF
Output capacitance	Coss			102		pF
Reverse transfer capacitance	Crss			77	108	pF
Gate resistance	Rg	Vgs=0V, Vds=0V, f=1MHz	1.5	3.0	3.6	Ω
SWITCHING PARAMETERS						
Total gate charge (10V)	Qg	Vgs=10V, Vds=15V, Id=5.8A		13.88	17.00	nC
Total gate charge (4.5V)	Qg			6.78	8.10	nC
Gate-source charge	Qgs			1.80		nC
Gate-drain charge	Qgd			3.12		nC
Turn-on delay time	td(on)	Vgs=10V, Vds=15V Rl=2.7 Ω, Rgen=3 Ω		4.6	6.5	ns
Turn-on rise time	tr			3.8	5.7	ns
Turn-off delay time	td(off)			20.9	30.0	ns
Turn-off fall time	tf			5.0	7.5	ns
Body diode reverse recovery time	trr	If=5.8A, dl/dt=100A/μ s		16.1	21.0	ns
Body diode reverse recovery charge	Qrr	If=5.8A, dl/dt=100A/μ s		7.4	10.0	nC

NOTE :

- The value of R_{θja} is measured with the device mounted on 1in² FR-4 board of 2oz. Copper, in still air environment with Ta=25°C. The value in any given applications depends on the user's specific board design, The current rating is based on the t ≤ 10s thermal resistance rating.
- Repetitive rating, pulse width limited by junction temperature.
- The R_{θja} is the sum of the thermal impedance from junction to lead R_{θjl} and lead to ambient.
- The static characteristics in Figures 1 to 6 are obtained using 80μs pulses, duty cycle 0.5%max.
- These tests are performed with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with Ta=25°C. The SOA curve provides a single pulse rating.

■ Typical electrical and thermal characteristics

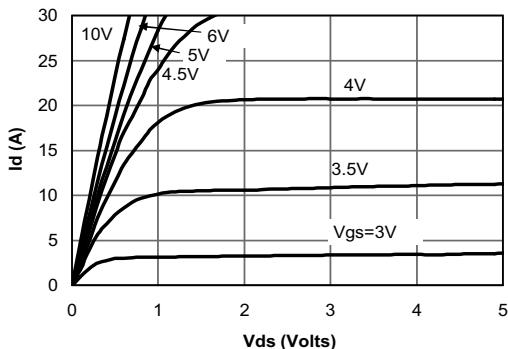


Fig 1: On-Region Characteristics

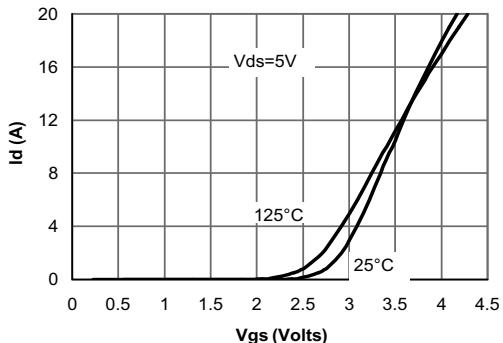


Figure 2: Transfer Characteristics

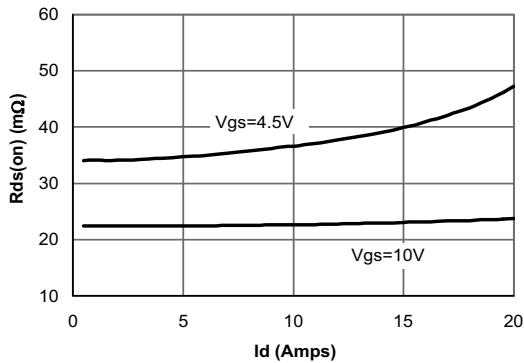


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

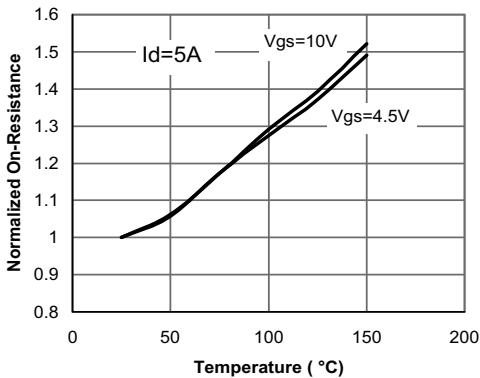


Figure 4: On-Resistance vs. Junction Temperature

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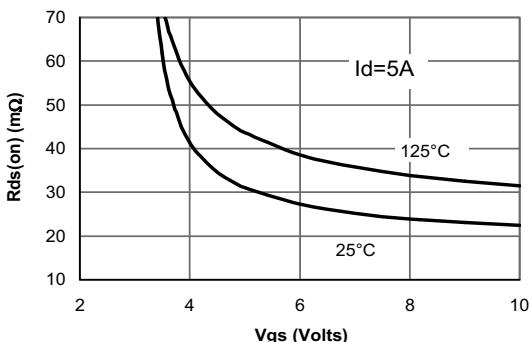


Figure 5: On-Resistance vs. Gate-Source Voltage

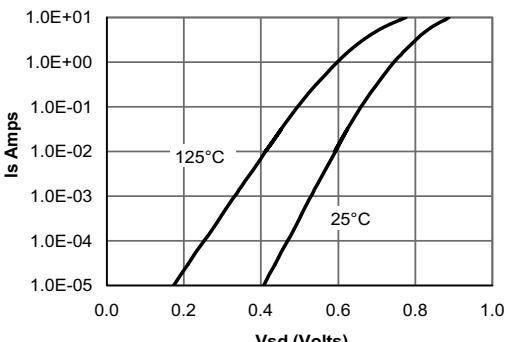


Figure 6: Body diode characteristics

